



Material Content Data Sheet



Sales Product Name	TLE6208-6G			Issued	19. July 2018			
MA#	MA001224136							
Package	PG-DSO-28-41			Weight*	835.28 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	14.425	1.73	1.73	17269	17269
leadframe	inorganic material	phosphorus	7723-14-0	0.073	0.01		87	
	non noble metal	zinc	7440-66-6	0.292	0.03		349	
	non noble metal	iron	7439-89-6	5.837	0.70		6988	
wire	non noble metal	copper	7440-50-8	237.007	28.37	29.11	283746	291170
	non noble metal	copper	7440-50-8	1.265	0.15	0.15	1514	1514
	encapsulation	organic material	carbon black	1333-86-4	1.131	0.14		1355
encapsulation	plastics	epoxy resin	-	52.045	6.23		62308	
	inorganic material	silicondioxide	60676-86-0	512.526	61.35	67.72	613599	677262
leadfinish	non noble metal	tin	7440-31-5	4.913	0.59	0.59	5882	5882
plating	noble metal	silver	7440-22-4	1.897	0.23	0.23	2272	2272
glue	plastics	epoxy resin	-	0.967	0.12		1158	
	noble metal	silver	7440-22-4	2.901	0.35	0.47	3473	4631
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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